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(12) **United States Design Patent**
Hsu

(10) **Patent No.:** **US D656,107 S**
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(54) **LIGHT EMITTING DIODE PACKAGE**

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(73) Assignee: **Lextar Electronics Corp.**, Hsinchu (TW)

(**) Term: **14 Years**

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(22) Filed: **Jun. 29, 2011**

(30) **Foreign Application Priority Data**

Jan. 7, 2011 (TW) 100300100

(51) **LOC (9) Cl.** **13-00**
(52) **U.S. Cl.** **D13/180**
(58) **Field of Classification Search** D13/180; D26/1, 2; 257/79, 80, 81, 88, 89, 95, 98, 257/99, 100, E33.058; 313/483, 498, 500; 362/555, 800

See application file for complete search history.

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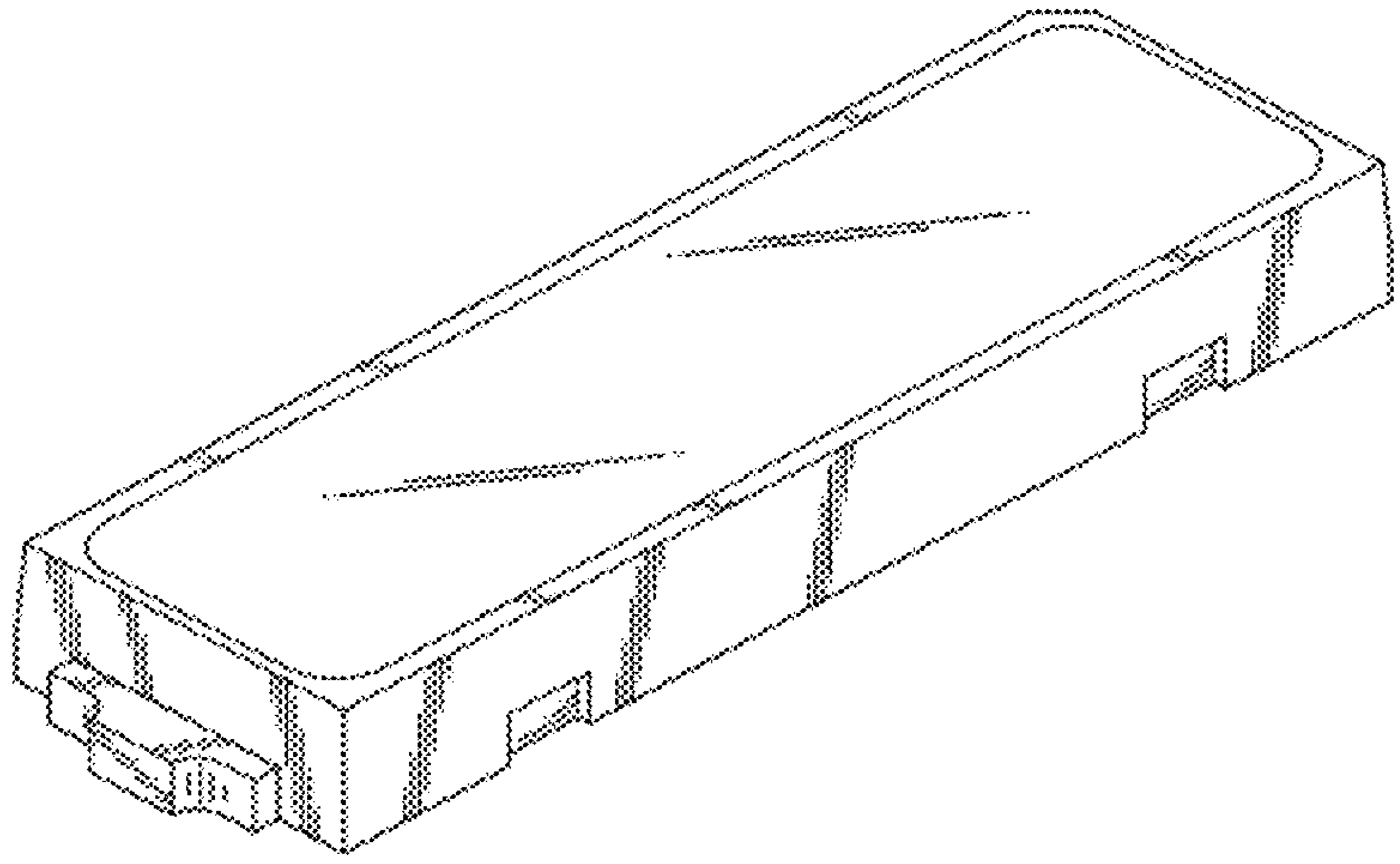
(57) **CLAIM**

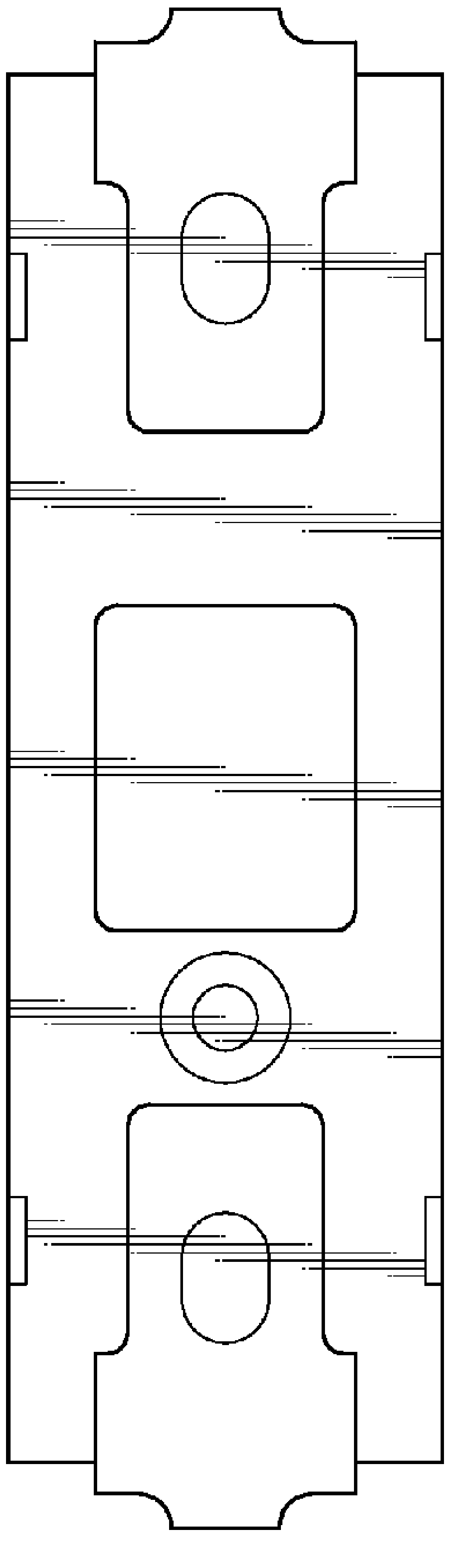
I claim the ornamental design for light emitting diode package, as shown and described.

DESCRIPTION

FIG. **1** is a front perspective view of light emitting diode package showing the new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 4 Drawing Sheets





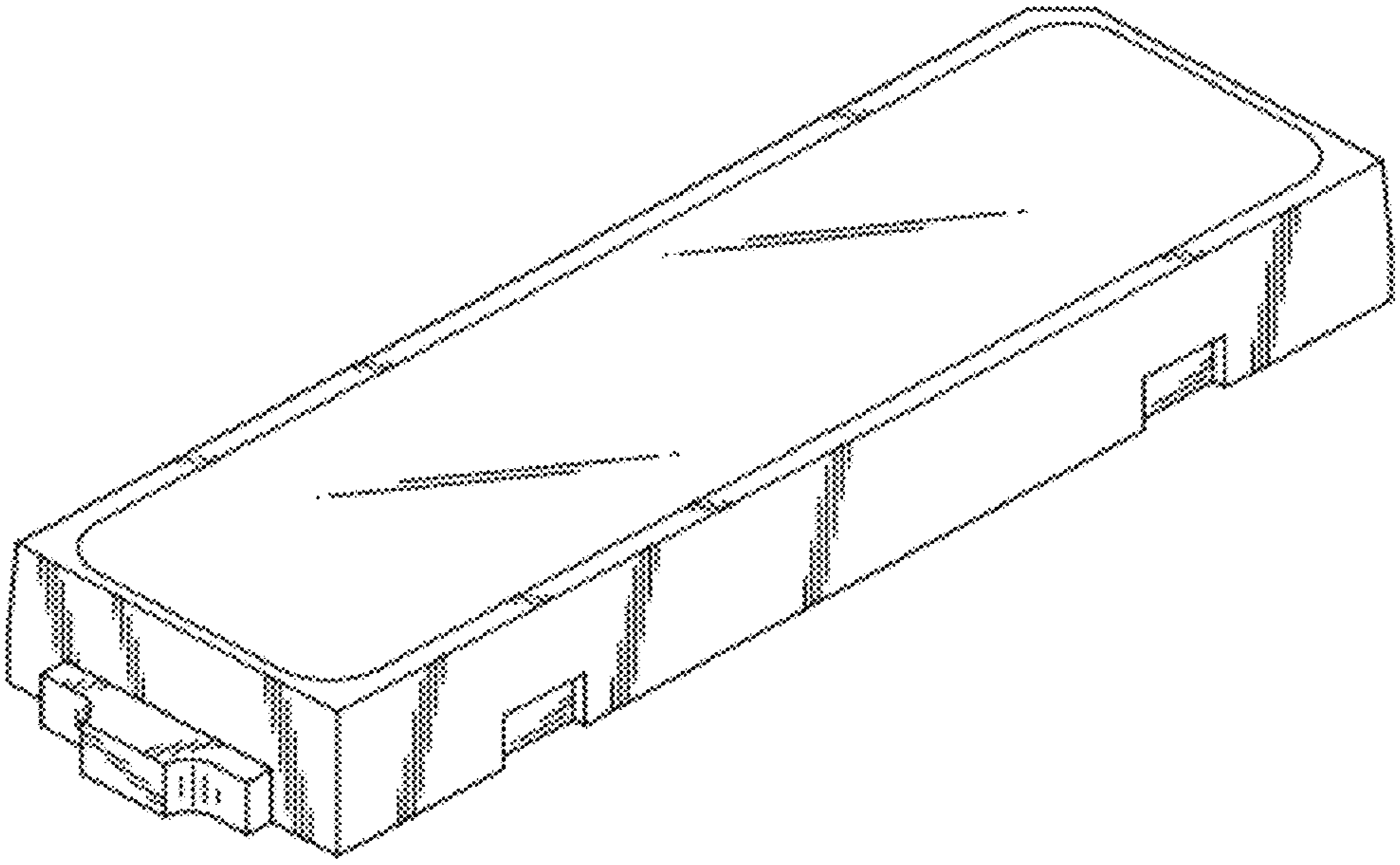


FIG.1

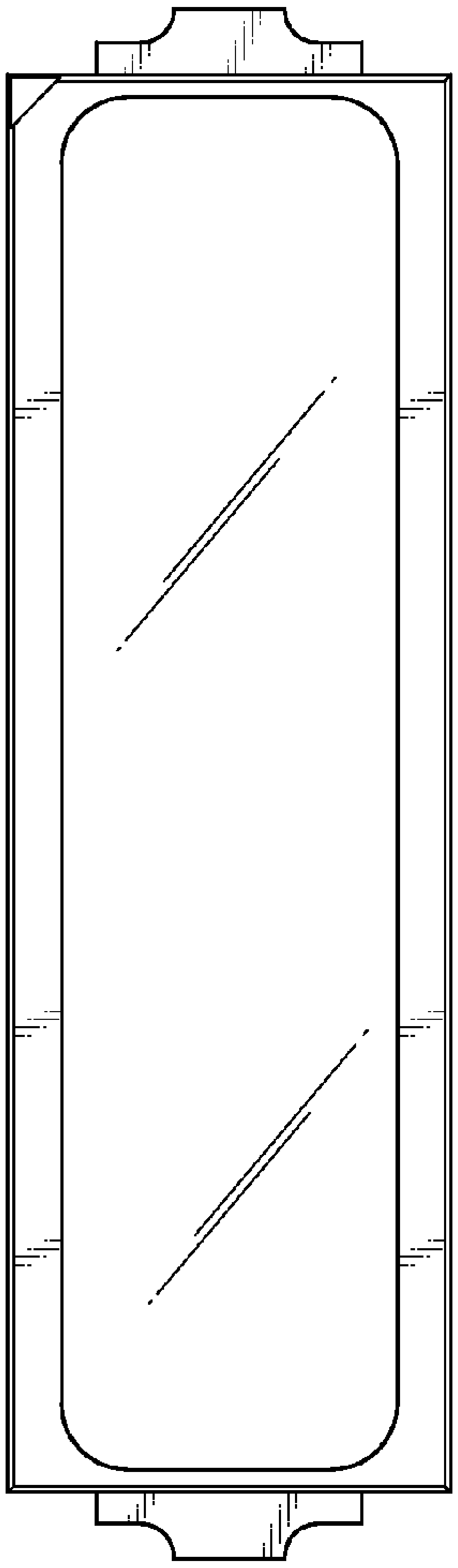


FIG.2

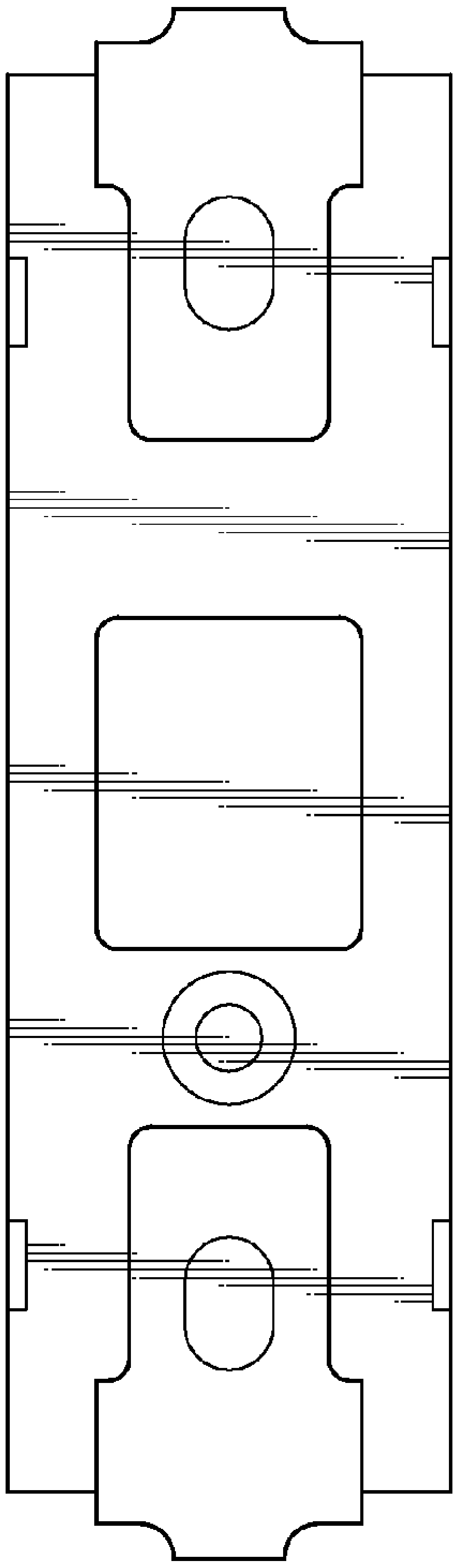


FIG.3

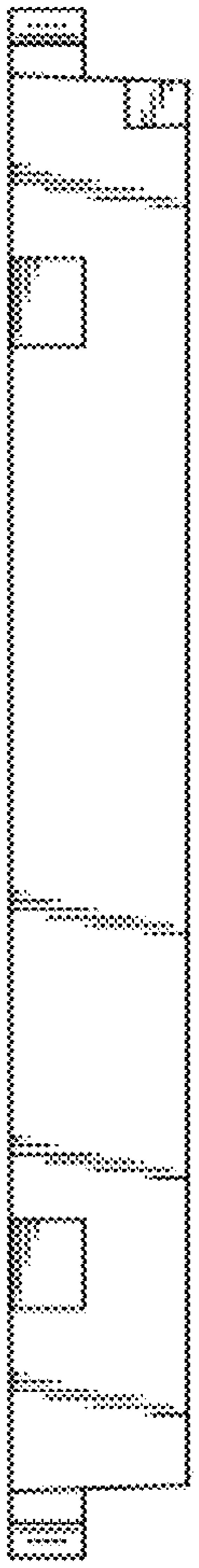


FIG.4

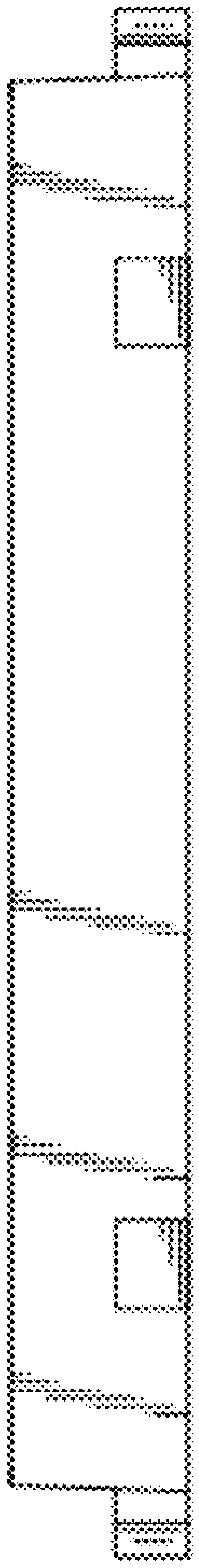


FIG.5

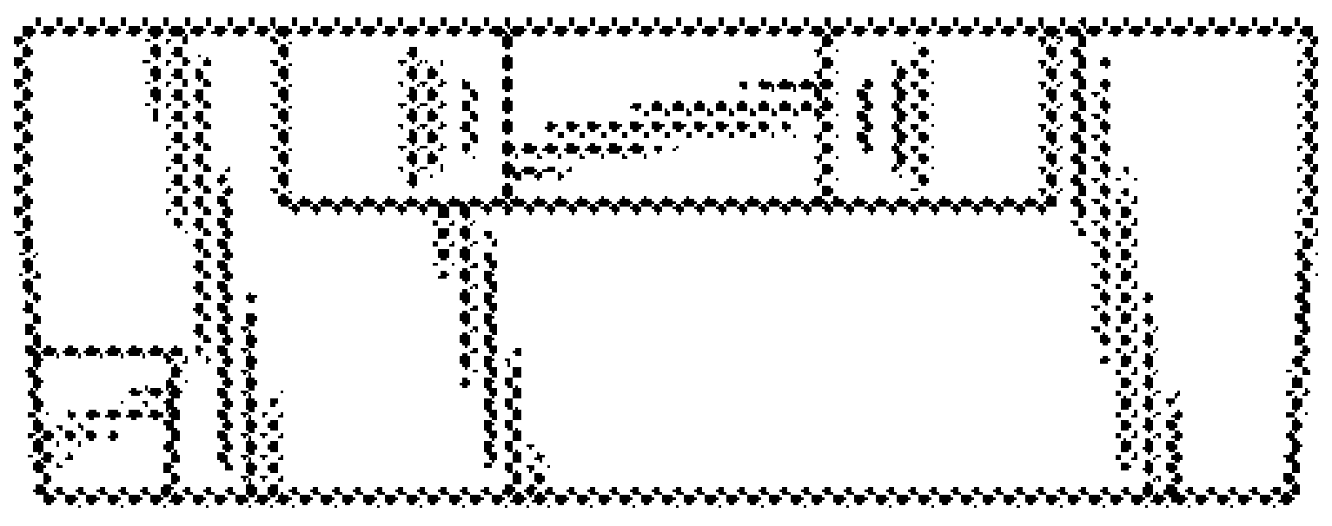


FIG.6

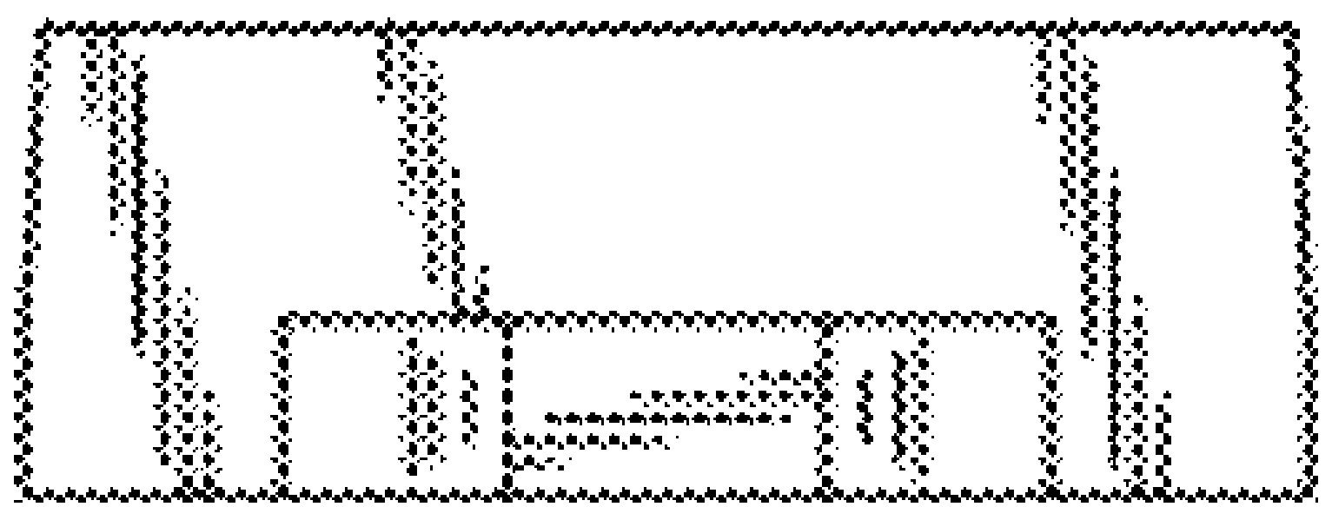


FIG.7